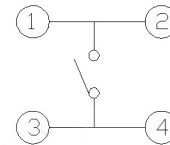
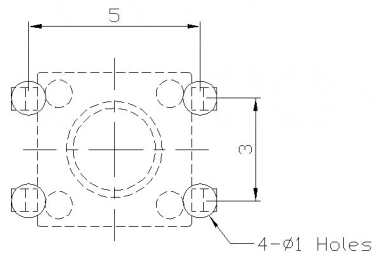
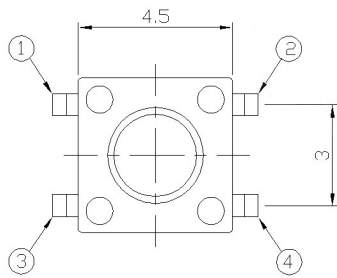


CIRCUIT DIAGRAM



Code-X	H
A	3.8
B	4.3
C	4.5
D	5.0
E	5.5
F	6.0
G	6.5
H	7.0
I	7.5
J	8.0
K	8.5
L	9.0

P.C.B MOUNTING PATTERN DIMENSION
The following soldering patterns are recommended for reflow soldering



SPECIFICATION

Contact Rating : 50mA, 12V DC
 Contact Resistance : 100mΩ max
 Insulation Resistance : 100mΩ min. 500V DC
 Dielectric Strength : 250V AC/1minute
 Travel : 0.25mm
 Operating Temp : -30 °C ~ +85 °C
 Storage Temp : -30 °C ~ +80 °C

PAPT NO	TC-1109-X-X
Operating Force	A: 100gf B: 160gf C: 260gf
Height	Code-X

ITEM	PAPT NAMF	TER.NO	QTY	MATERIAL	FINISHING	REMARK
⑤	Terminal	---	4	Brass (0.30t)	Plating silvering	---
④	Contact	---	1	F.ag/Sus	Natural	---
③	Base	---	1	Pa46	---	---
②	Cover	---	1	Spcc	Plating Nickel	---
①	Keystake	---	1	Pa46	---	---

						DSND		DATE		SCALE: N/A	MODEL TYPE:		
						DWN		DATE		VIEW:	TACT SWITCH		
						CHKD		DATE		UNIT: mm	PART NO.:		
						APPD		DATE		SIZE: A4	DWG NO.:		
						KOSOD TECHNOLOGY CO., LTD					TC-1109-X-X		
											WEIGHT	SHEET	REVISION
											1.0g	1/1	A0

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
Δx					units: mm
Δx					tolerance: X.X ±0.2mm
Δx					X.XX ±0.1mm
					X.XXX ±0.05mm